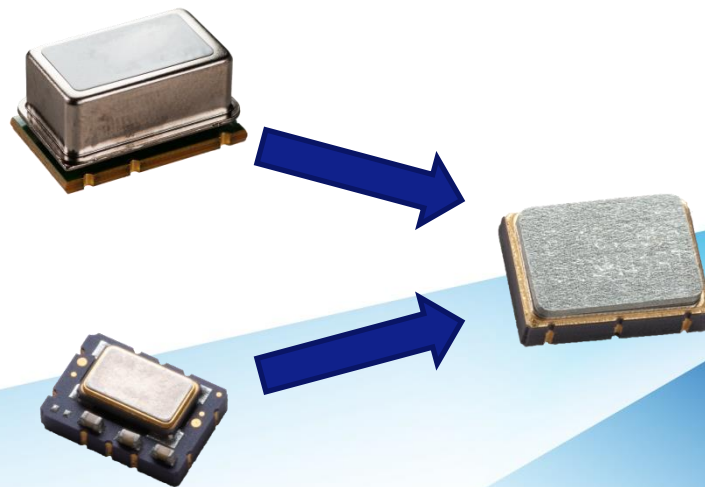
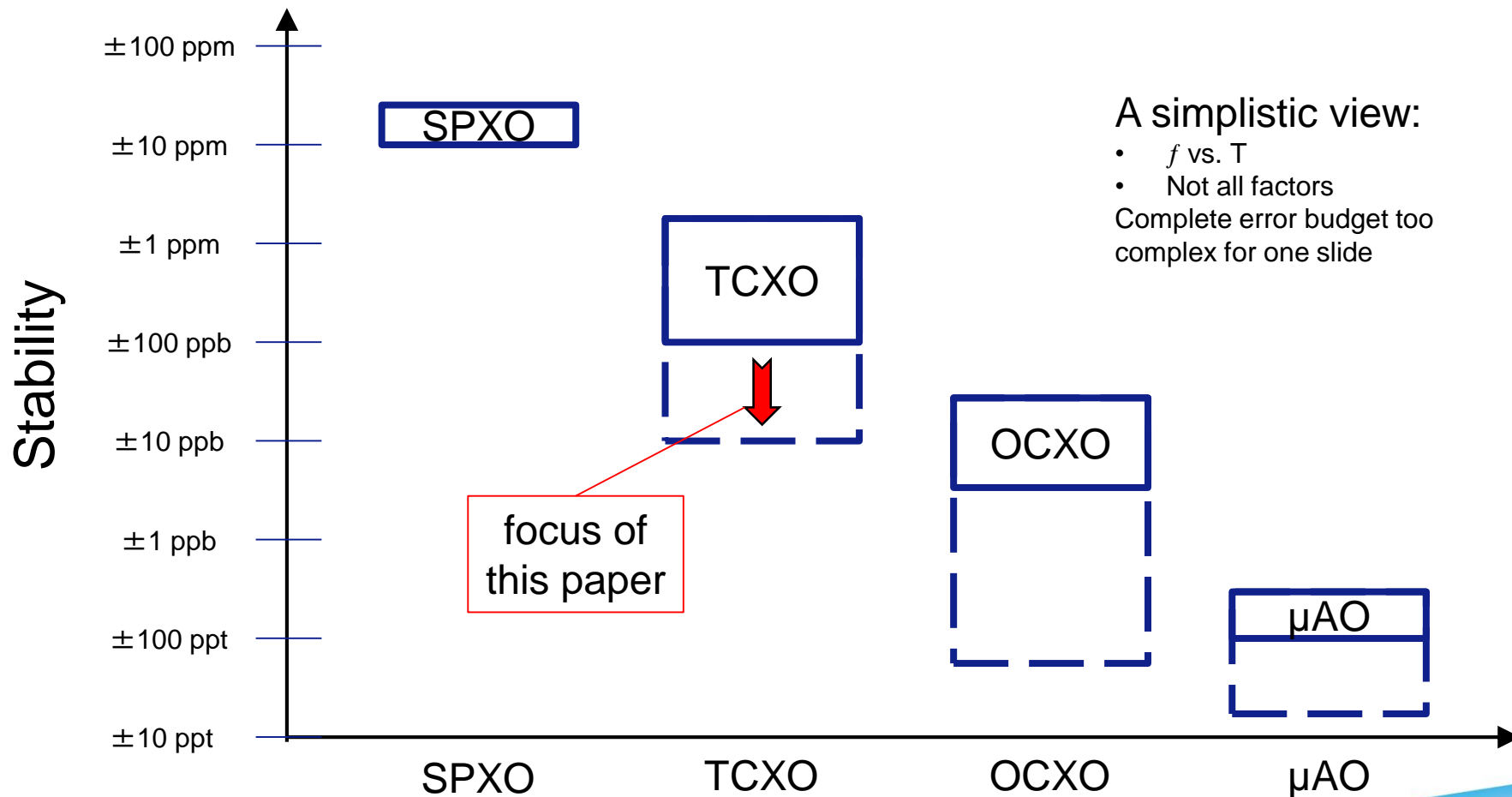


# The Next Frontier in TCXO Performance

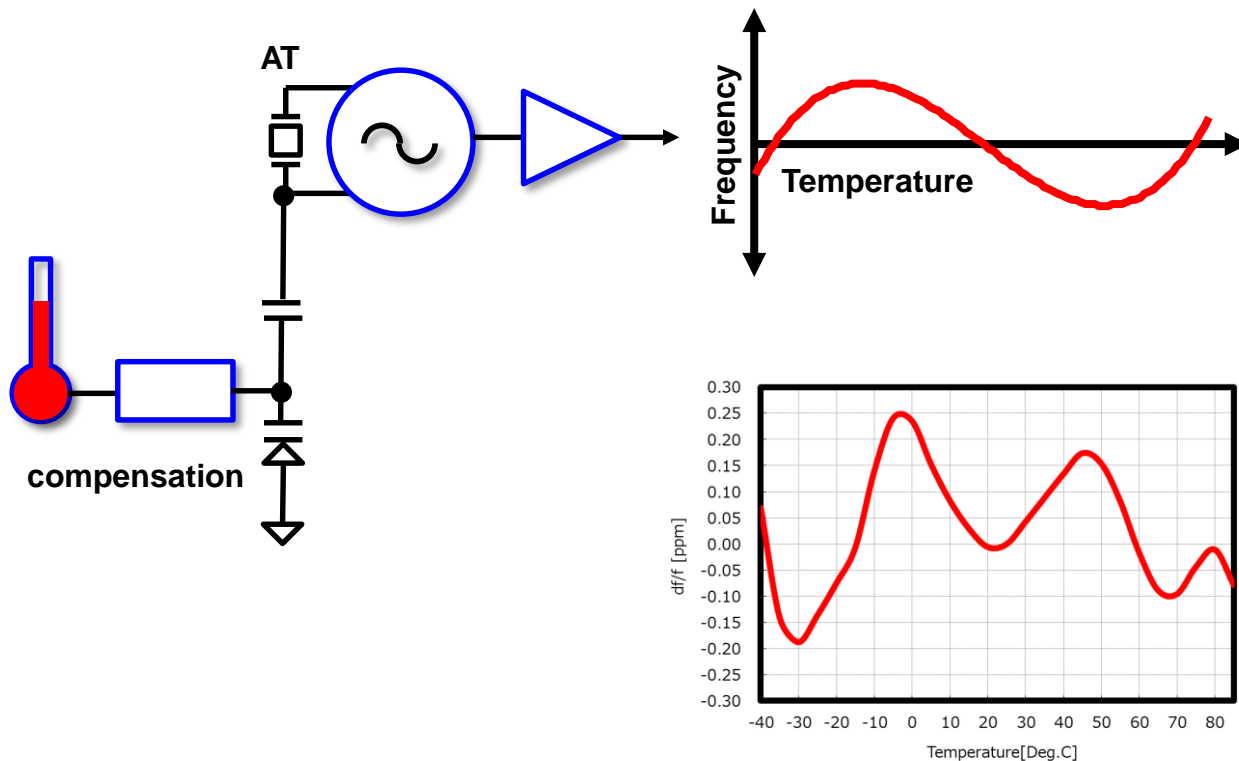
**Chris McCormick**  
**Allan Armstrong**  
**WSTS 2018**  
June 21, 2018



# Where are we today?



# Basics – How a TCXO Works



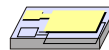
$$f \text{ vs. } T \approx \pm 10 \text{ ppm}$$
$$< \pm 20 \text{ ppm}$$

controlled by:

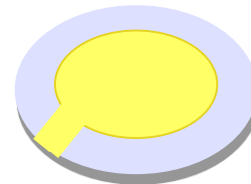
- cut angle
- crystal shape
- crystal dimensions

$f$ vs. $T$	Compensation
$\pm 2 \text{ ppm}$	10x
$\pm 1 \text{ ppm}$	20x
$\pm 0.5 \text{ ppm}$	40x
$\pm 0.28 \text{ ppm}$	70x
$\pm 0.1 \text{ ppm}$	200x
$\pm 0.01 \text{ ppm}$	2000x

# Basics – How an OCXO Works

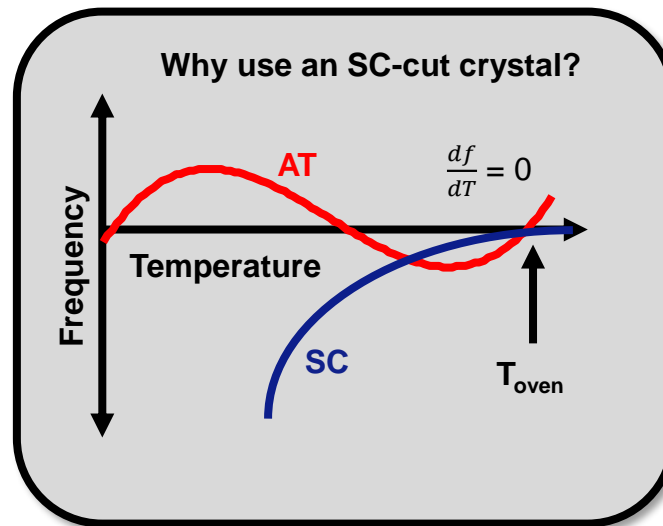
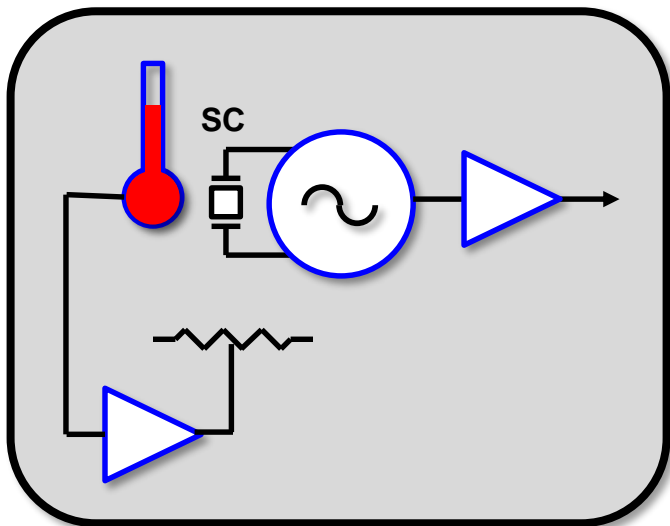


AT



SC

- Size
- Shape
- Cut angle
- Stress



# Characteristics of TCXOs vs. OCXOs

## What We have Today

### Performance

	TCXO	OCXO
<i>f</i> vs. T	±0.1-0.28 ppm	± 10-50 ppb
ADEV @ 1s	1E-9	1E-10
Aging 20-yr	< ±3 ppm	< ±1 ppm
Aging 24-hr	< ±40 ppb	< ±1 ppb
Airflow	ok	Much better



### Practicality

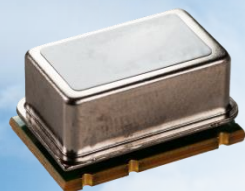
	TCXO	OCXO
Size (WxL)	5x3.2	25x22 21x13 14x9
Size (H)	1.5-2.0	9-12
Cost	\$\$	\$\$\$
Power	<< 30 mW	< 1-2.5 W
Reliability	Much better	ok



# What Else Needs to be Done?

## Performance

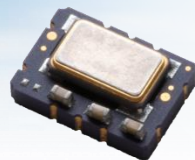
- $f$  vs.  $T$
- Wander
- Aging
- Holdover
- Airflow



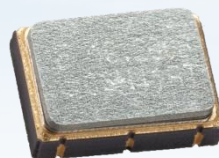
OCXO

## Practicality

- Size
- Cost
- Power
- Reliability



TCXO



next-gen  
oscillator

## How do we get there?

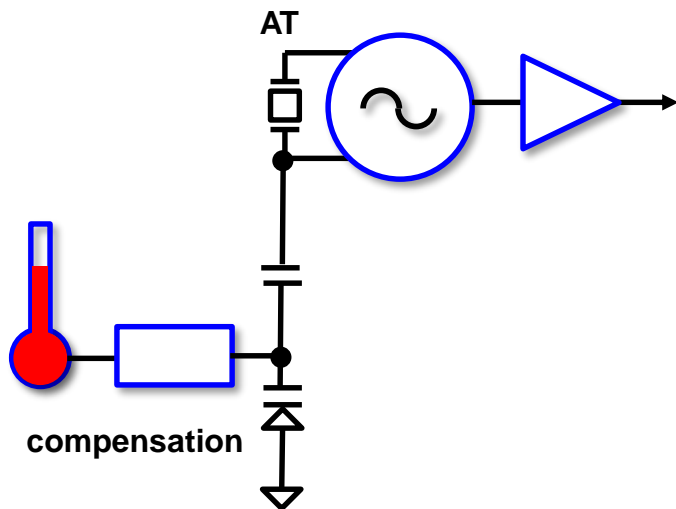
- Compensation & Calibration Techniques
- SPC & Manufacturing Discipline
- IC Design
- Mechanical & Thermal Design
- Packaging Technology
- Crystal Design & Fabrication Techniques

# How can we make TCXOs perform like OCXOs?

## Existing State of the Art – Recent Innovations

1. **IC design & calibration techniques** –  $f$  vs.  $T$
2. **XTAL design** – wander
3. **Package & structure** (thermal design) – airflow & stability for small  $T$  variations

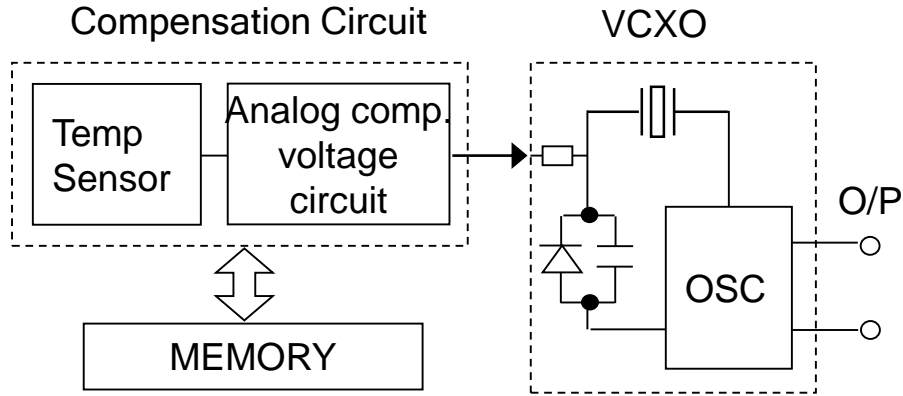
## What do we need to do next?



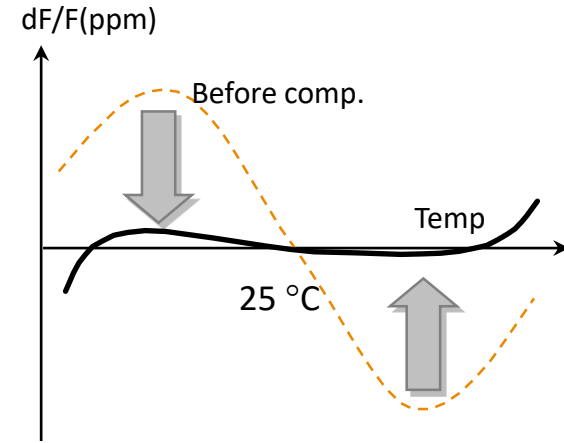
## 2 Important Choices:

1. Analog vs. Digital
2. How do you compensate?

# Analog Compensation



**Analog Compensation Method**

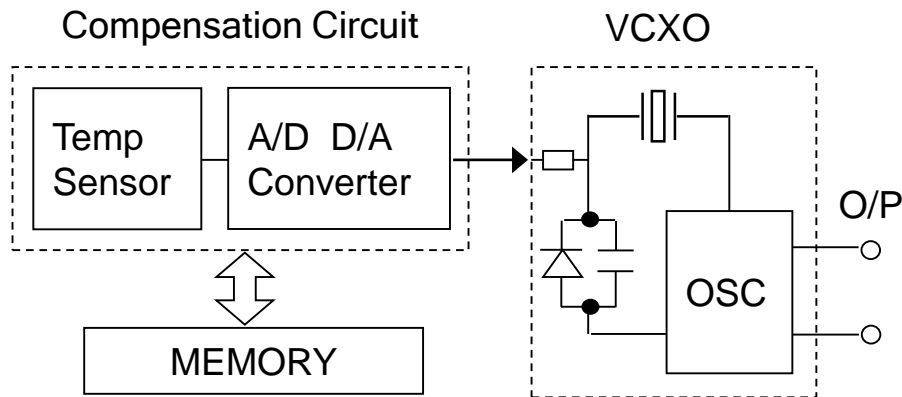


**Advantage:** No discrete phase jumps

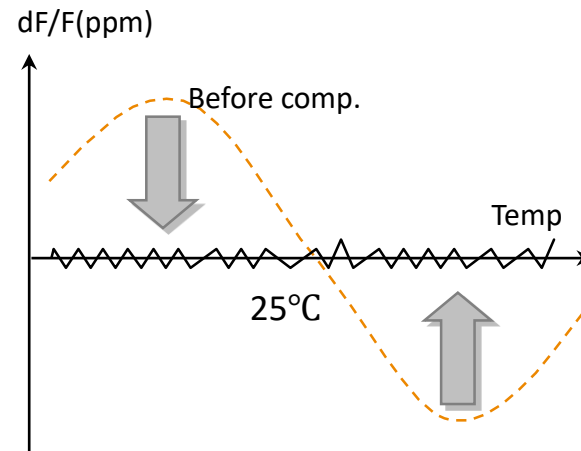
**Challenge:** fitting error

- Crystal cutting & design optimization
- Calibration techniques – accuracy vs. cost

# Digital Compensation



Digital Compensation Method



**Advantage:** less fitting error (lots of points!)

**Challenge:** discrete phase jumps

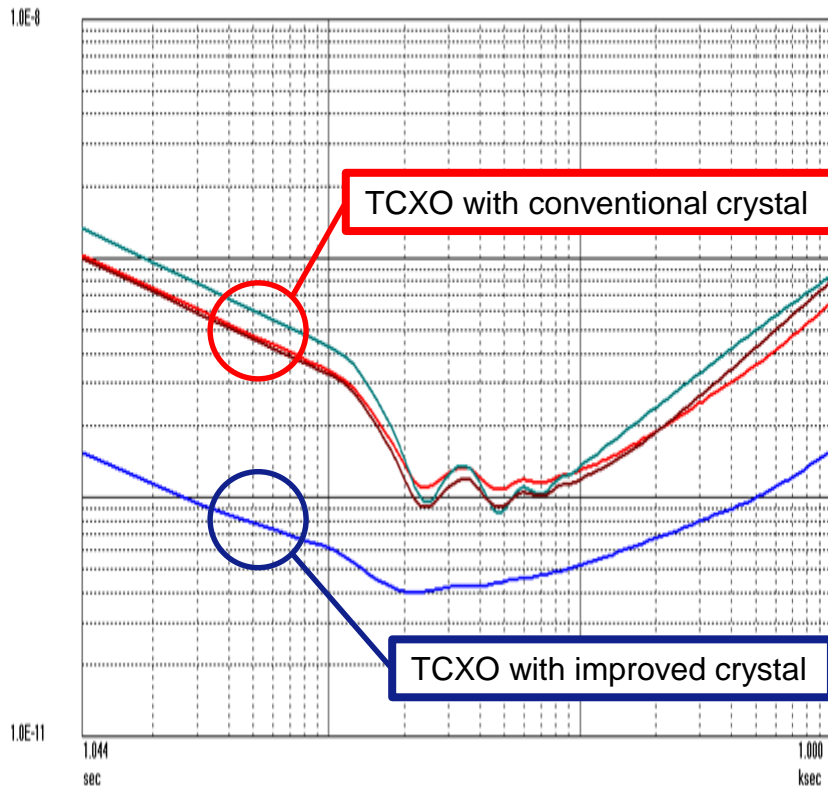
- Easy answer: resolution < stability
- How well can you measure temperature? How well do you know your crystal?

# Short-Term Stability (Wander)

Microsemi TimeMonitor Analyzer (file=01187.dal)

Root Allan Variance; Overlapping Samples; Fo=20.00 MHz; Fs=957.4 mHz; 2016/05/13; 09:21:25

**ADEV**

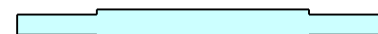
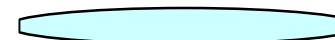
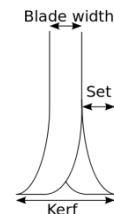


## Crystal Design Improvements

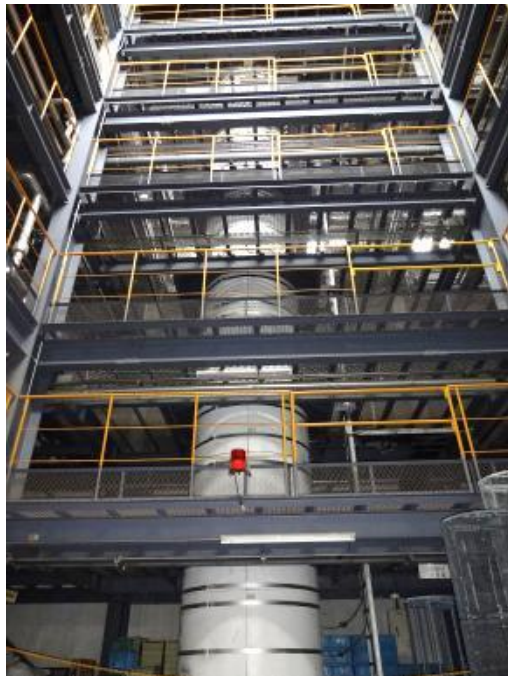
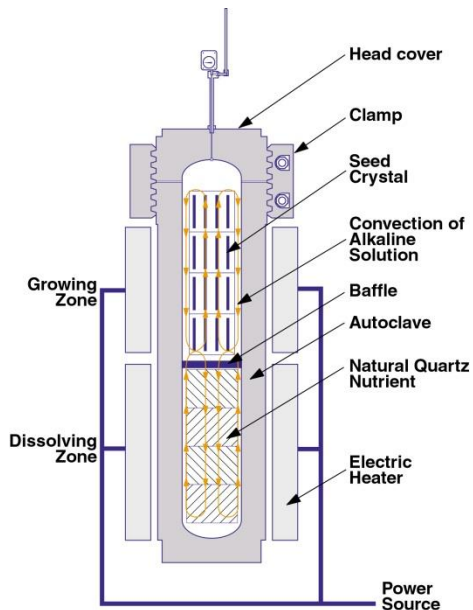
### ① Material Purity



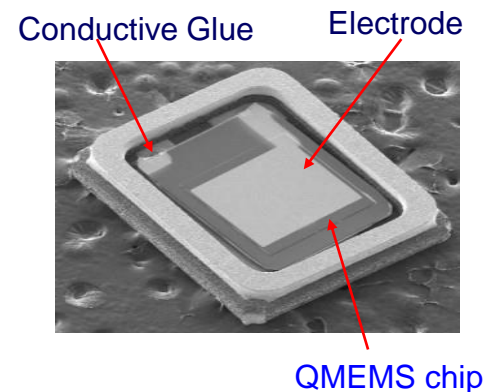
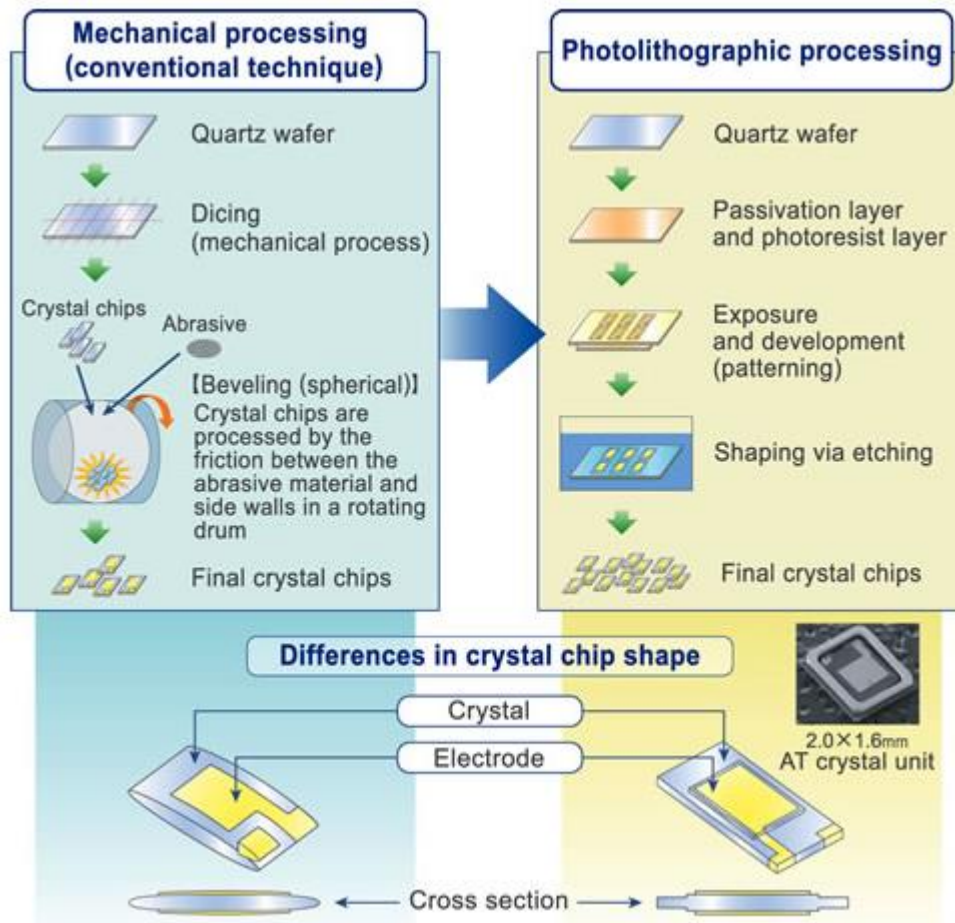
### ② Crystal Processing



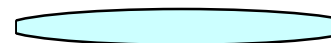
# Material Purity (Autoclave)



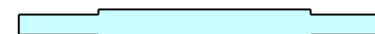
# Crystal Processing



## Resulting Shape (cross section)



Mechanical  
(beveled)



Epson QMEMS  
(photolithographic)

# Why TCXOs are Sensitive to Airflow



airflow

Cold

Hot

Temperature  
Sensitive  
Element

Temperature  
sensor

PCB

## Fundamental Mechanism

- Temperature-sensitive element (crystal) and temperature sensor (IC) are not in the same place

- Airflow causes Temperature gradient

- How sensitive is Quartz?

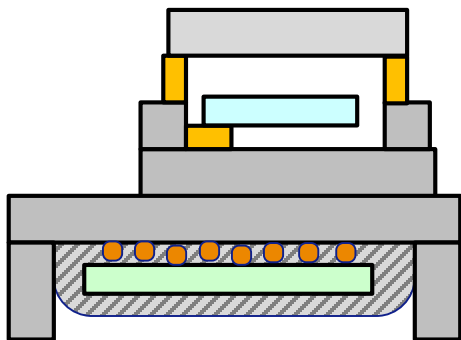
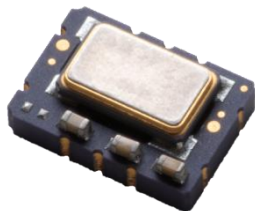
$$\frac{df}{dT} = \frac{20 \text{ ppm}}{60^\circ\text{C}} = 0.3 \text{ ppm}/^\circ\text{C}$$

vs. 30 ppm/°C for Silicon

- How much temperature gradient can we tolerate?

$$1 \text{ ppb} \div 0.3 \text{ ppm}/^\circ\text{C} = 0.003^\circ\text{C}$$

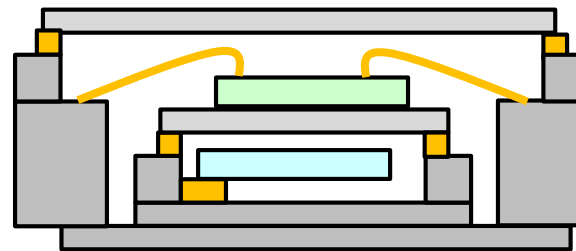
# Construction – Double-Decker vs. DoubleSeal™



## Double-Decker

Phase transients due to to airflow

- Crystal and IC not thermally coupled



## DoubleSeal™

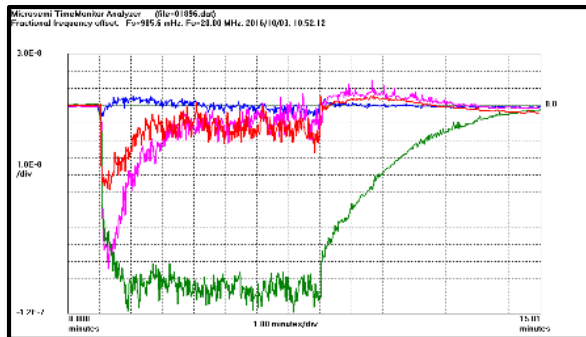
Better Thermal Design

- Protected from airflow and board turbulence
- More stable for small T changes

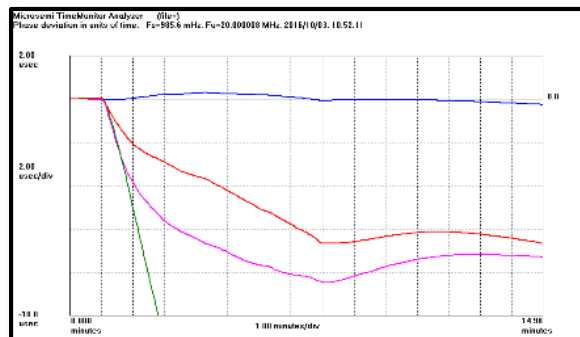
US & Japanese patents

# The Advantage of DoubleSeal™ Technology

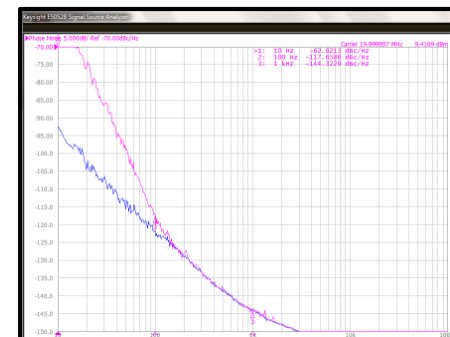
## Performance under Airflow



**Better Frequency Stability**  
**3-25x**



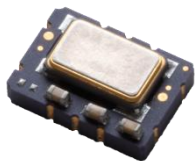
**Better Phase Stability**  
**1-250x**



**Better Phase Noise**  
**30 dB @ 10 Hz**

## Dependable Synchronization

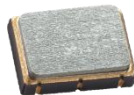
# Comparison of Specs



**Conventional  
TCXOs**



**DoubleSeal™  
TCXO**



**Future  
TCXO**



**Current  
OCXOs**

Aging	±3 ppm	±3 ppm	<< 1 ppm	±1 ppm
Initial	±1 ppm	±1 ppm	±1 ppm	±500 ppb
vs. T	±0.1-0.28 ppm	±0.1-0.28 ppm	→ ±10 ppb	±10 ppb
vs. V	±0.1 ppm	±0.1 ppm	→ ±10 ppb ✓	±10 ppb
vs. C <sub>L</sub>	±0.1 ppm	±0.1 ppm	→ ±10 ppb ✓	±10 ppb
<b>TOTAL</b>	<b>&lt; ±4.6 ppm</b>	<b>&lt; ±4.6 ppm</b>	<b>&lt; ±4.6 ppm</b>	<b>&lt; ±4.6 ppm</b>
24-hour drift	±40 ppb	±5 ppb	→ ±1 ppb	< ±1 ppb
ADEV (1s)	1E-9	2E-10	→ 1E-10	0.5-1E-10

# So how close are we? Next Steps?

## Where are we now?

- TCXOs easily meet S3, but not S3E
- Many PTP systems need OCXOs
- TCXOs getting a **lot** better

## Solved problems

- Greatly improved wander due to improved crystal design
- Airflow issues solved with thermal design techniques
- 24-hour drift getting a **lot** better, approaching OCXOs

## What's next?

- Improve  $f$  vs.  $T$  through calibration techniques –  $\pm 100$  ppb  $\rightarrow$   $\pm 10$  ppb
- Further improvement of wander and 24-hour drift

## How soon can this be done?

# THANK YOU

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Satoru Kodaira  
Takashi Kumagai

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